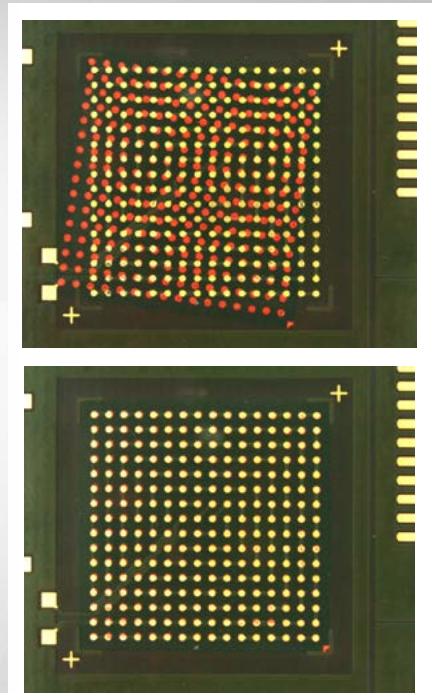




Component alignment of a BGA on the HR 500..

HR 500

Repair assemblies professionally and price-consciously.

The Ersa HR 500 Hybrid Rework System is the first choice for all common rework tasks on medium-sized SMD assemblies. The system is suitable for desoldering, placing and soldering PLCC, QFP and BGA components as well as MLF components or bipolar elements up to an edge length of 1 x 1 mm.

Like all Ersa Hybrid Rework systems, the HR 500 is equipped with a powerful hybrid top heater. Its bottom-side heater consists of highly dynamic infrared heating elements which can be switched in two zones.

The component alignment is carried out by means of fine drives and high-resolution camera images of the Visionbox. Components are set down almost powerlessly with the aid of a stepper motor with fine switch-off. The device convinces overall by its intuitive operation and the flexibility in the application

The HR 500 is prepared to accept an Ersa Dip & Print frame, the component printing with solder paste is done externally on the Ersa DIP & PRINT STATION. The dip-in of a component into a flux depot is motor-driven. For process observation and documentation, the device can optionally be equipped with a powerful reflow process camera with LED illumination.

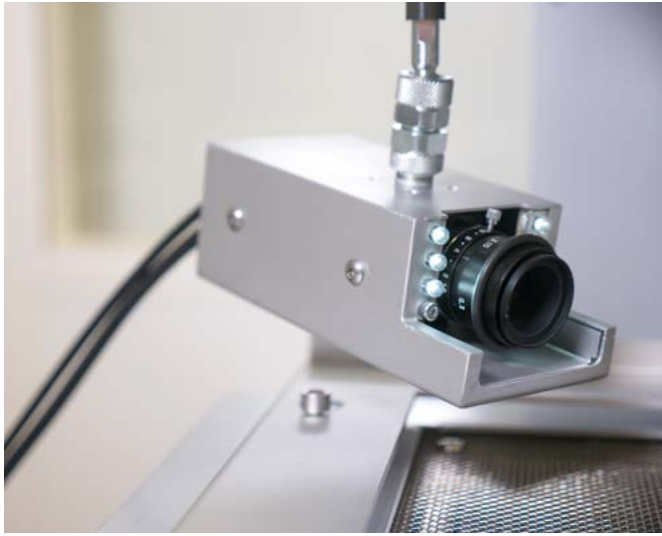
The HRSoft 2 operating software (for Windows™) supports the user in all work processes and documents them. HRSoft 2 allows the connection of Ersa rework systems to customer MES systems.

Technical highlights:

- 800 W hybrid high-power heating element
- Full-area 1,600 W IR bottom heater
- High-resolution cameras for placement and process monitoring
- Ergonomically optimal system operation
- Modern, user-friendly operating software



High-power hybrid heater



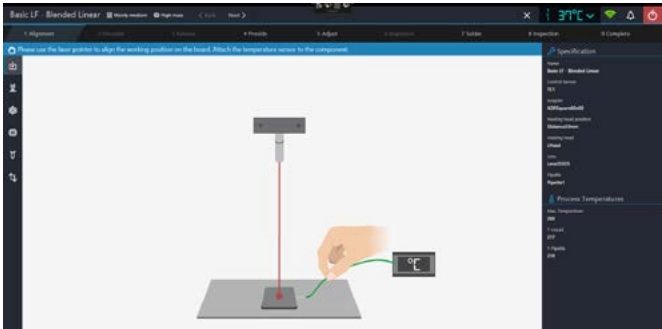
Optional reflow process camera.

Technical data:

Dimensions (W x D x H)	655 x 645 x 710 mm
Weight	approx. 55 kg
Ausführung antistatisch	yes
Nominal power	2,400 W
Nonminal voltage	220 V – 240 VAC, 50 – 60 Hz, 16 A
Top heater	Hybrid emitter 800 W, 70 x 70 mm
Bottom heater	IR emitter (2 x 800 W), 270 x 270 mm
Measurement channels	2 x K-type
Position laser	Class II
Board size	up to 380 x 300 mm (+x)
Component size	from 1 x 1 mm up to 50 x 50 mm
Working depth	340 mm
Working distance	60 mm to top heater 35 mm to bottom heater
Placement camera	5 MP GigE color camera , field of vision 50 x 50 mm
Certification mark	CE
Operating software	HRSOft 2 – suitable for Windows 8 and Windows 10
Option – reflow process camera	2,3 MP CMOS GigE color camera 25 mm focal length illumination 2 x LED, adjustable

Order information:

Artikelnummer	Beschreibung
OHR500	Ersa HR 500 Hybrid Rework System
OHR510	RPC camera HR 550
OPR100	DIP & PRINT STATION , complete



HRSOft 2 with intuitive operation surface.



Flexible PCB holder.



further information
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